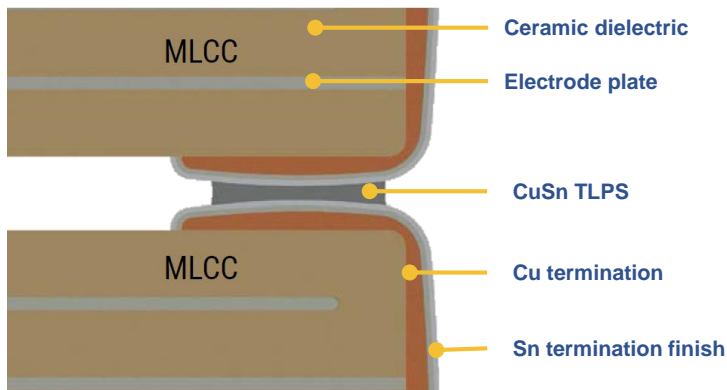




Overview

KEMET's X7R with KONNEKT™ technology surface mount capacitors are designed for applications where higher capacitance and voltage are needed without requiring additional board space. KONNEKT high density packaging technology uses an innovative Transient Liquid Phase Sintering (TLPS) material to create a surface mount multi-chip solution for high density packaging.

Construction



Benefits

- Commercial and Automotive grade (AEC-Q200)
- Higher capacitance values in smaller areas.
- Lead (Pb)-free, RoHS, and REACH compliant
- Surface mount capable with standard reflow

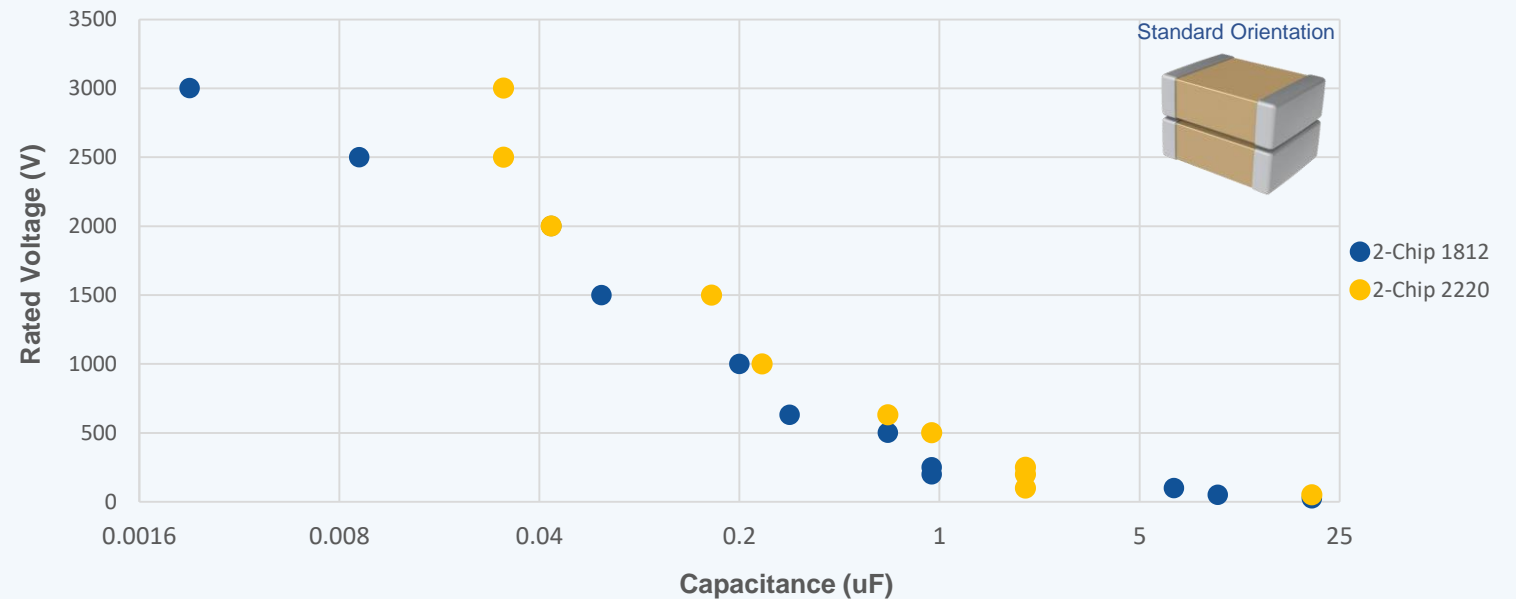
Electrical Characteristics

Operating Temperature	-55°C to +125°C
Rated Capacitance	2.4 nF – 20 uF (±10% tol.)
Rated Voltage	25 V – 3,000 V
EIA Case Size	1812 and 2220

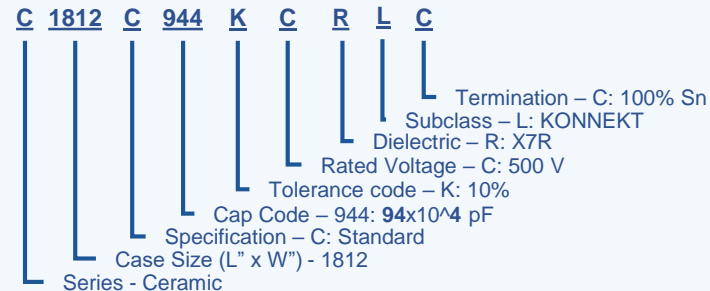
MULTILAYER CERAMIC CAPACITORS

X7R with KONNEKT Technology

X7R with KONNEKT Selection Guide



Part Number System



<https://ec.kemet.com/konnekt>